

HYBRID INTERGRATED THERMAL ELECTRIC AND EJECTOR ACTIVE COOLING SYTEM

The current active thermal electric cooling system being used for electronic components or systems has a low coefficient of performance (COP) which directly limits the application. The invention is a hybrid of both thermal electric and ejector refrigeration systems which can significantly increase the COP of the active cooling system. And it has no moving parts and the effect of the temperature difference across the thermal electric cooling module on the system COP can be significantly reduced.

POTENTIAL AREAS OF APPLICATIONS:

- Electronic cooling
- Computer chip thermal management
- Laser cooling

PATENT STATUS: Provisional patent application on file

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